

CONDUCTIVE POLYMER INTERCONNECTION CONFIGURATIONS

ABSTRACT OF THE DISCLOSURE

A method of forming an electrical connection between two devices is disclosed. In an exemplary embodiment of the invention, the method includes soldering a second solderable cap of an interconnection to a first contact pad of a first component. The interconnection further includes a conductive polymer comprising a polymer component and a conductive component. A first solderable cap is disposed in contact with the conductive polymer, and the second solderable cap is disposed in contact with the conductive polymer opposite the first solderable cap. The first solderable cap is then soldered to a second contact pad of a second component.